ORDERING INFORMATION

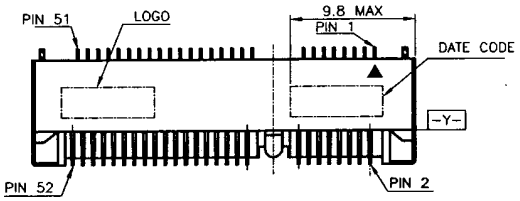
SERIES NO.	CONN.TYPE	PIN NO	HEIGHT	HOUSING MATERIAL	CONTACT PLATING	PEG PLATING	PEG	PACKING	POST	LOGO	REMARKS
650	S	52	8	1	XX	XX	M	43	1	X	X

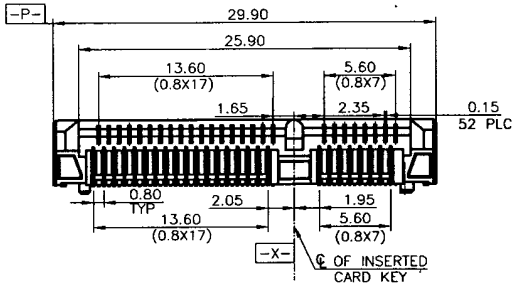
S: STANDARD
52PIN
8: 5.2mm
1: LCP BLACK
51: SELECTION GOLD 1μ"OVER Ni 50 μ"
20: MATTE-TIN
30: BRIGHT-TIN
M: ME
43: TAPE&REEL (44mmB4)
1: WITH POST
N: NO LOGO
2: AP LOGO
0: OBVERSE PACKING
1: REVERSE PACKING

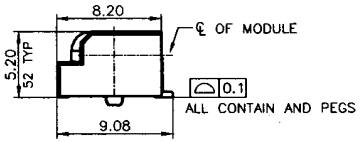
52: SELECTION GOLD 5μ"OVER Ni 50μ"
57: GOLD PLATING 10μ"OVER Ni 50μ"
61: GOLD PLATING 1μ"OVER Ni 50μ"
62: GOLD PLATING 3μ"OVER Ni 50μ"
71: CONTACT AREA AND SOLDER AREA : SELECTION GOLD 1μ"OVER Ni 50~80μ"
72: CONTACT AREA AND SOLDER AREA : SELECTION GOLD 3μ"OVER Ni 50~80μ"

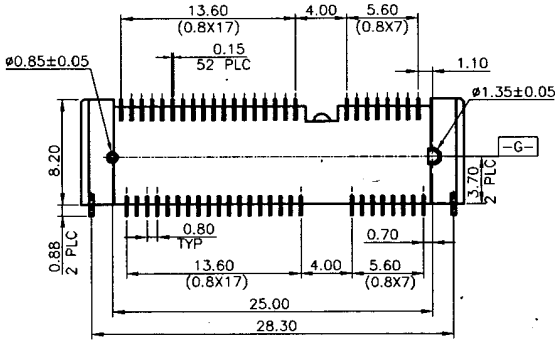
MATERIAL
▲THIS PART DON'T CONTAIN ANY SUBSTANCES WHICH ARE SPECIFIED IN SS-00259
HOUSING : THERMO PLASTIC UL94V-0 BLACK
CONTACT : COPPER ALLOY
PEG : COPPER ALLOY

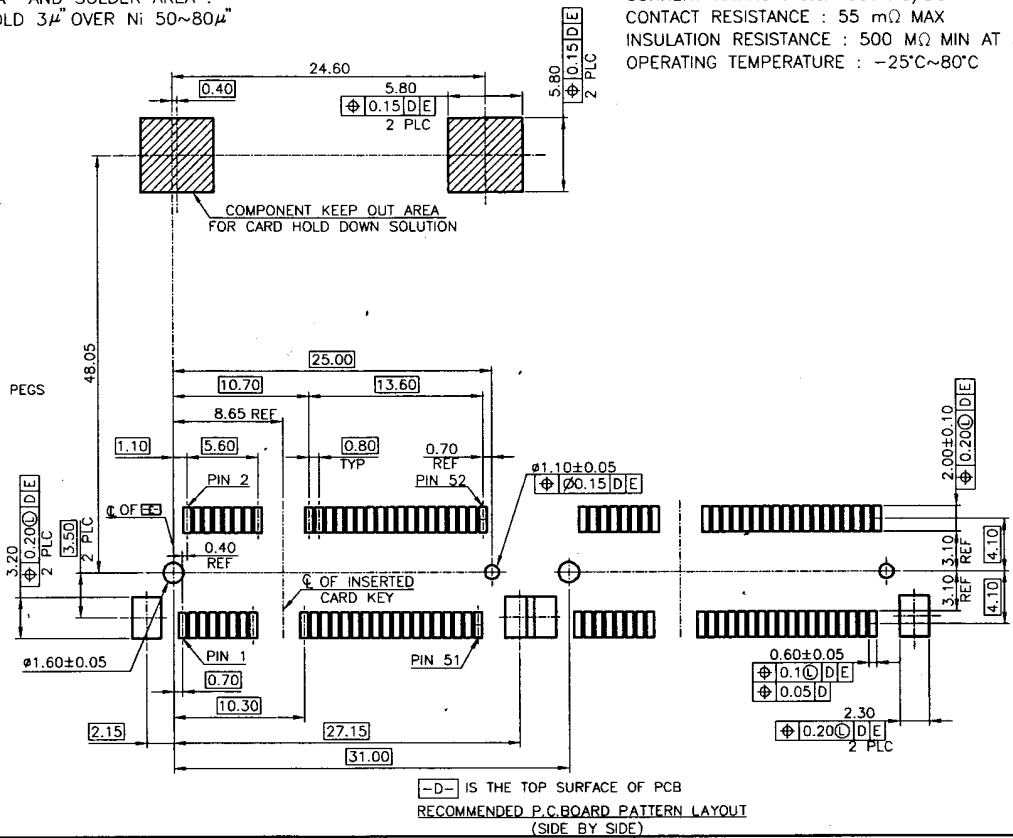
SPECIFICATION
CURRENT RATING : 0.5A 50V AC/DC
CONTACT RESISTANCE : 55 mΩ MAX
INSULATION RESISTANCE : 500 MΩ MIN AT 500V DC
OPERATING TEMPERATURE : -25°C~80°C











-D- IS THE TOP SURFACE OF PCB

RECOMMENDED P.C.BOARD PATTERN LAYOUT (SIDE BY SIDE)

REV.	REVISION RECORD	DATE
A	INITIAL RELEASE	01/13/10'

General Tolerances
LINEAR 0.0 ±0.30, 0.00±0.20
ANGLES±3°
UNIT: mm

	NAME	DATE
APPROVED		
DESIGNER		
DRAWN	Knight Chang	1/14-10'

TITLE: 0.80MM PITCH MINI PCI EXPRESS H=5.2mm CONNECTOR CUSTOMER DRAWING

DWG.NO.: S650S5281XXXXM431XX REV. A

SCALE 1 : 1 SHEET 1 OF 1